


<p><b>Features</b></p> <ul style="list-style-type: none"> <li>• Low profile space</li> <li>• Ideal for automated placement</li> <li>• Glass passivated chip junctions</li> <li>• Low forward voltage drop</li> <li>• Low leakage current</li> <li>• High forward surge capability</li> <li>• High temperature soldering : 260°C/10 seconds at terminals</li> </ul> <p><b>Mechanical Data</b></p> <ul style="list-style-type: none"> <li>• <b>Case:</b> SOD-323 molded plastic body over glass passivated chip</li> <li>• <b>Terminals:</b> Solder plated, solderable per JESD22-B102</li> <li>• <b>Polarity:</b> Laser band denotes cathode end</li> </ul>	 <p><b>SOD-323</b></p> <p><b>ROHS COMPLIANT</b></p> <p><b>Major Ratings and Characteristics</b></p> <table border="1"> <tr> <td><math>I_{F(AV)}</math></td> <td><b>1 A</b></td> </tr> <tr> <td><math>V_{RRM}</math></td> <td><b>50 V to 1000 V</b></td> </tr> <tr> <td><math>I_{FSM}</math></td> <td><b>10A</b></td> </tr> <tr> <td><math>I_R</math></td> <td><b>5 <math>\mu</math>A</b></td> </tr> <tr> <td><math>V_F</math></td> <td><b>1.15V</b></td> </tr> <tr> <td><math>T_j \text{ max.}</math></td> <td><b>125. C</b></td> </tr> </table>	$I_{F(AV)}$	<b>1 A</b>	$V_{RRM}$	<b>50 V to 1000 V</b>	$I_{FSM}$	<b>10A</b>	$I_R$	<b>5 <math>\mu</math>A</b>	$V_F$	<b>1.15V</b>	$T_j \text{ max.}$	<b>125. C</b>
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**Maximum Ratings & Thermal Characteristics**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Items	Symbol	1N4001WS A1	1N4002WS A2	1N4003WS A3	1N4004WS A4	1N4005WS A5	1N4006WS A6	1N4007WS A7	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L = 90^\circ\text{C}$	$I_{F(AV)}$	1							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	10							A
Thermal resistance from junction to lead <sup>(1)</sup>	$R_{\theta JL}$	35							$^\circ\text{C}/\text{W}$
Operating junction range	$T_J$	-55 to +125							$^\circ\text{C}$
storage temperature range	$T_{STG}$	-55 to +125							$^\circ\text{C}$

Note 1: Mounted on PCB with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

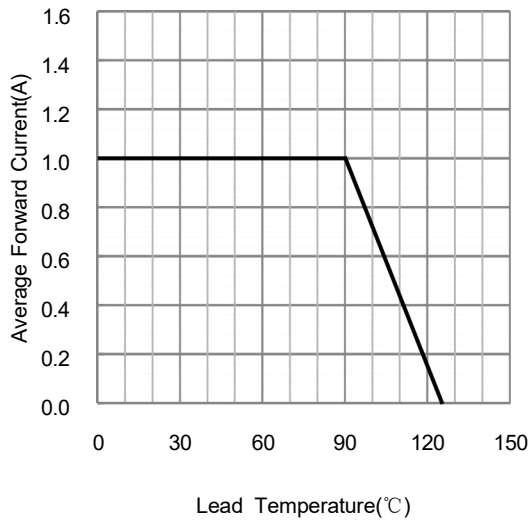
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Items	Test conditions	Symbol	Min	Type	Max	UNIT
Instantaneous forward voltage	$I_F = 0.5\text{A}$	$V_F$	-	0.95	-	V
	$I_F = 1\text{A}^{(2)}$			1	1.15	
Reverse current	$V_R = V_{DC}$	$I_R$	-	-	5	$\mu\text{A}$
					$T_A = 125^\circ\text{C}$	

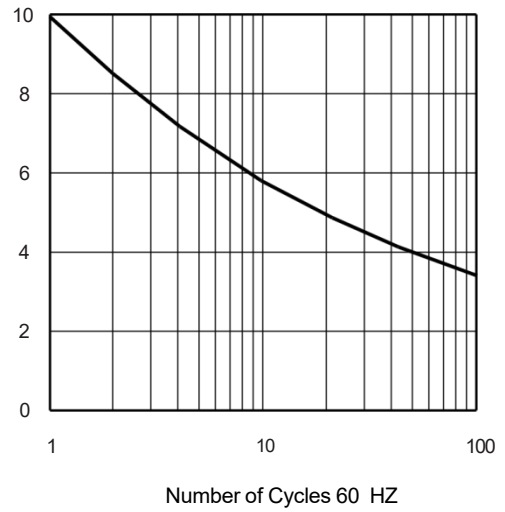
Note 2: Pulse test:300 $\mu$ s pulse width,1% duty cycle.

### Typical Characteristic Curves ( $T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

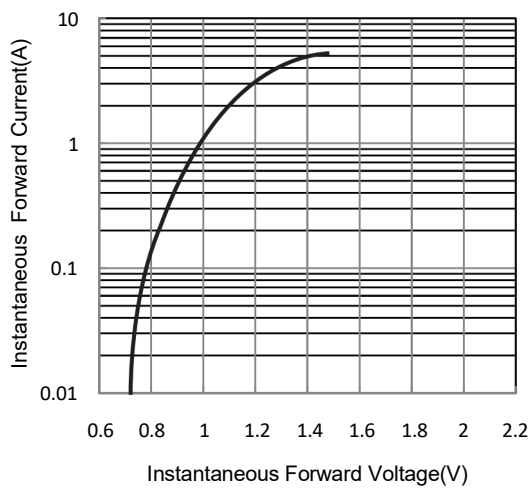
**Fig.1 Forward Current Derating Curve**



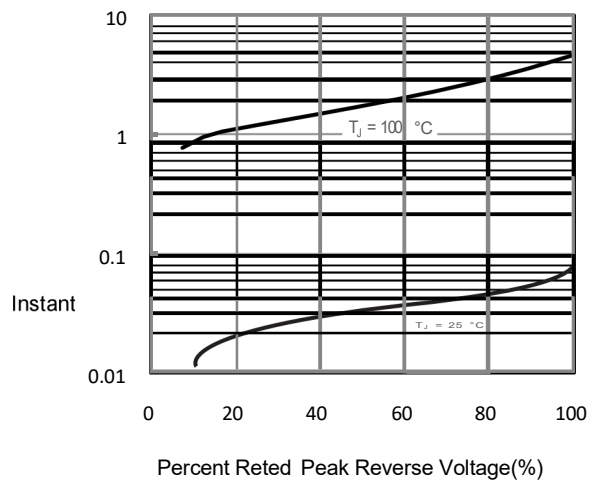
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**



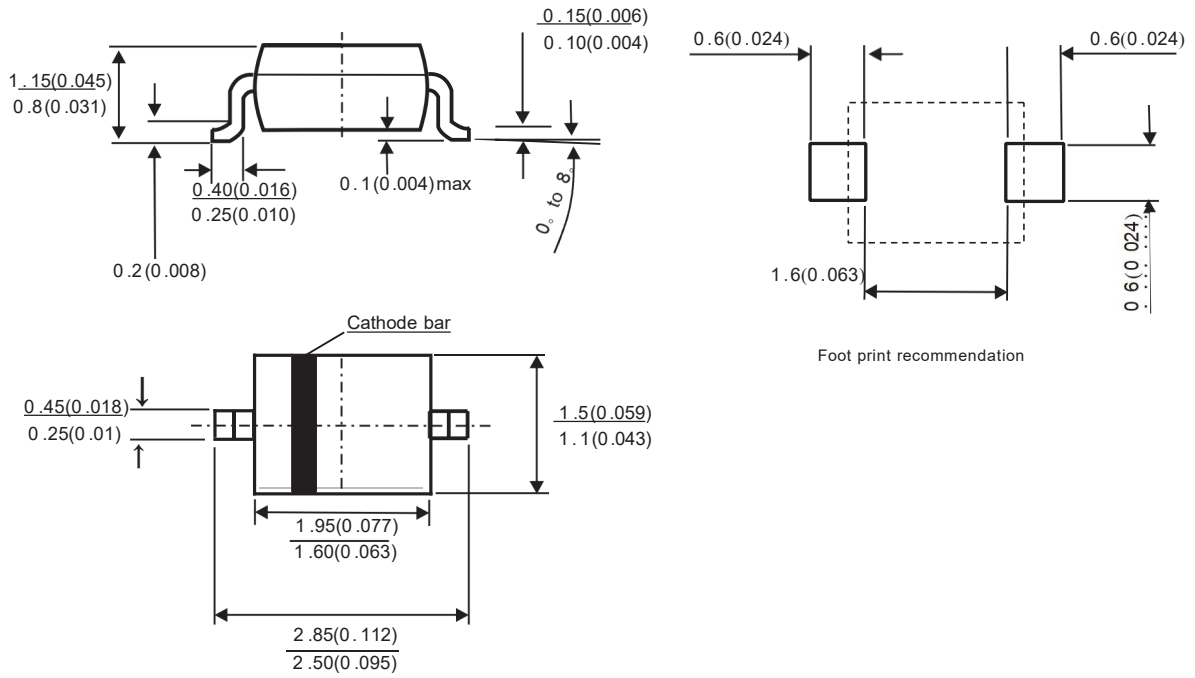
**Fig.3 Typical Instantaneous Forward Characteristics**



**Fig.4 Typical Reverse Leakage Characteristics**



## Package Outline



Dimensions in millimeters and (inches)